**Att. No 1**

**Firs part of the order SDM-WS/26**

**ORDER DESCRIPTION – InP N**

1. **Object of the contract**

The subject of the order is the supply of semiconductors wafers listed below by name and quantity needed:

1. InP N 3” DSP 15 pieces

2. InP N 4” DSP 50 pieces

3. InP N 4” SSP 50 pieces

4. InP N 6’’ DSP 25 pieces

1. **The scope of the subject of the contract**

A detailed description of the subject of the contract is provided in section 5 of this document.

1. **Criterion**

Offers will be evaluated according to a point scale with a maximum number of points of 100.

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| --- | --- | --- |
| Criterion | Maximum number of points S | Method of awarding points |
| Price net (P) | 100 | S x Pmin/Pi |

Where:

* Pi – net price of goods with delivery - for the given offer
* Pmin - the minimum delivery net price for the ordered goods from all offers submitted
* S – number of points

The final score will be calculated by adding up the partial components and then rounded to two decimal places. (rounded from "5" up)

1. **Deadline for completing the order**

Up to 7 weeks from the date of order.

1. **Parameters**

|  |  |  |
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| Product name | Parametrer | Specification |
| **InP N-type** **Doped with S**  | Diameter 3”Thickness: 600±30 µmDiameter: 76.0±0.3 mm | Grade: | Prime, Epi-ready |
| Orientation: | (100)±0.3o |
| Primary Flat: | EJ (0-1-1) ±0.5o |
| Diameter 100mmThickness: 620±25 µmDiameter: 100±0.4 mm | Secondary Flat | EJ (0-11) ±0.5o |
| Carrier Conc.: | Min 1E18/cm3 |
| Diameter 6”Thickness: 650±30 µmDiameter: 150±0.4 mm | EPD (Average): | ≤4000/cm2 max |
| Surface Finish: | DSP (double side polished) Side 1: Polished Side 2: Polished |
| 4” also SSP (single side polished) Side 1: Polished Side 2: Etched |
| Packaging: | 3” and 4” wafers: ePAK, individual box, sealed with N2 in a moisture-stopping metallic foil bag, done in class 100 clean room. |
|  |  | 6” wafers: cassette, sealed with N2 in a moisture-stopping metallic foil bag, done in class 100 clean room. |